

Sumikon® EME-7720TA

Epoxy; Epoxide
Sumitomo Bakelite Co., Ltd.

Message:
Sumikon 7700-Series compounds are multi-functional-type molding compounds developed for overmolded BGA packages.

General Information			
Features	Good cracking resistance		
Uses	Semiconductor molding compound		
Forms	Liquid		
Processing Method	Enclosure		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	2.00	g/cm ³	ASTM D792
Water Absorption (24 hr)	0.33	%	ASTM D570
Mechanical	Nominal Value	Unit	Test Method
Flexural Modulus (25°C)	20600	MPa	ASTM D790
Flexural Strength (25°C)	177	MPa	ASTM D790
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	195	°C	ASTM E1356
Thermal Conductivity	0.79	W/m/K	ASTM C177
Electrical	Nominal Value	Unit	Test Method
Volume Resistivity	1.0E+13	ohms·cm	ASTM D257
Thermoset	Nominal Value	Unit	
Demold Time (175°C)	0.50 - 1.7	min	
Post Cure Time (175°C)	2.0 - 8.0	hr	

Additional Information
Spiral Flow, SB-U-03-003: 130 cmGel Time, SB-U-03-005, 175°C: 27 secThermal Expansion, SB-U-02-002, TTg: 4.0 E-5/°CFlexural Strength, SB-U-01-001, 240°C: 34.3 MPaFlexural Modulus, SB-U-01-002, 240°C: 2453 MPaUL-94 Flame Class, SB-U-03-003: V-0Extracted Na+, SB-U-04-043: <5 ppmExtracted Cl-, SB-U-04-043: <10 ppmTransfer Pressure: 687-1177 MPa

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